Place one 1000pF cap close to each supply pin of the PHY.
To improve noise connect NR to GND through a cap.
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EMI Compliant Dual Port Industrial Gigabit Ethernet PHY

Project Title:

Designed for:

Assembly Variant:

TI Confidential - NDA

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Drawn By:
Engineer:

K. Mogensen
Texas Instruments

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Version control disabled

SVN Rev:

TIDA-00204

Number:
Rev:

E3

PCB Number:
PCB Rev: LOGO
PCB Pb-Free Symbol

FID2 FID1 FID3 FID5 FID4 FID6

CO!PCB1 COFID1 COFID2 COFID3 COFID4 COFID5 COFID6

COH1 COH2 COH3 COH4 COH5 COH6 COH7 COH8

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